

ABSTRACT

The invention relates to a gas distribution apparatus of semiconductor equipment in which parts are assembled in a simple way in a chamber to thereby improve job efficiency in assembling and disassembling operations and prevent gas leakage outside. The apparatus assembled to supply gas into a chamber for a plasma etching process comprises: a body having a plurality of gas inducing inlets on a downward grooved side of its plate; and an injection plate screwed with the bottom surface of the body, the injection plate having small and large diameters of ring-shaped grooves on its upper surface to connect the gas inducing inlets, the grooves having injection holes formed at a predetermined interval for downward penetration, so as to completely prevent gas leakage outside.